



# 100% Material Declaration Data Sheet FGG900 Spartan-6

PK469 (v1.0) Jul 29, 2011

**Average Weight: 3.949 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.090946</b>	<b>2.303</b>
	Silicon	7440-21-3	100.00	Main material	0.090946	
<b>Die Attach Material</b>					<b>0.016016</b>	<b>0.406</b>
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
<b>Mold Compound</b>					<b>1.876994</b>	<b>47.531</b>
	Solid Epoxy Resin	Trade Secret	5.00	Main material	0.093850	
	Phenol Resin	Trade Secret	5.00	Main material	0.093850	
	Fused Silica	60676-86-0	87.45	Main material	1.641431	
	Metal Hydroxide	Trade Secret	2.00	Main material	0.037540	
	Carbon Black	1333-86-4	0.55	Main material	0.010323	
<b>Gold Wire</b>					<b>0.023056</b>	<b>0.584</b>
	Gold	7440-57-5	99.05	Main material	0.022837	
	Palladium	7440-05-3	0.95	Main material	0.000219	
<b>Solder Balls</b>					<b>0.751829</b>	<b>19.038</b>
	Tin	7440-31-5	96.50	Main material	0.725515	
	Silver	7440-22-4	3.00	Main material	0.022555	
	Copper	7440-50-8	0.50	Main material	0.003759	
<b>Substrate</b>					<b>1.190159</b>	<b>30.138</b>
	Copper	7440-50-8	28.19	Main material	0.335483	
	Nickel	7440-02-0	4.13	Main material	0.049192	
	Gold	7440-57-5	0.30	Main material	0.003529	
	BT (core)	21645-51-2 7440-50-8 Epoxy resin	59.49	Main material	0.708012	
	Solder mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6	7.89	Main material	0.093943	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
07/29/11	1.0	Initial Xilinx release.

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